

Date: 01 Aug 2012

Product Category: Memory

Device Family:  

Notification subject: CCB 1148.01 Final Notice: Qualify 8L SOIC, package code SAE, with MSL level 1 at LPI assembly site.

Notification text: PCN Status:
Final notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as...
PCN_CYER-19IFTH566_Affected_CPN.xls
PCN_CYER-19IFTH566_Affected_CPN.pdf

Description of Change:
Qualify 8L SOIC, package code SAE, with MSL level 1 at LPI assembly site.

Pre Change:
MSL level 3

Post Change:
MSL level 1

Impacts to Data Sheet:
None

Reason for Change:
To improve manufacturability

Change Implementation Status:
In Progress

Estimated First Ship Date:
August 3, 2012 (date code: 1231)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
April 24, 2012: Issued initial notification.

August 1, 2012: Issued final notification. Attached qualification report.
Revised the estimated first ship date from 6/15/2012 to 8/3/2012.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_CYER-19IFTH566_Affected_CPN.xls](#) [PCN_CYER-19IFTH566_Affected_CPN.pdf](#) [PCN_CYER-19IFTH566_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

Product Change Notification - CYER-19IFTH566

Parts Affected

SST25LF020A
SST25VF010A
SST25VF020
SST25VF020B
SST25VF040B
SST25VF080B
SST25VF512
SST25VF512A

PCN_CYER-19IFTH566
CATALOG_PART_NBR
SST25LF020A-33-4C-SAE
SST25LF020A-33-4C-SAE-T
SST25LF020A-33-4C-SAE-TT078
SST25LF020A-33-4C-SAE-TT078-T
SST25LF020A-33-4E-SAE
SST25LF020A-33-4E-SAE-T
SST25LF020A-33-4I-SAE
SST25LF020A-33-4I-SAE-T
SST25VF010A-33-4C-SAE
SST25VF010A-33-4C-SAE-PP013
SST25VF010A-33-4C-SAE-PP013-T
SST25VF010A-33-4C-SAE-T
SST25VF010A-33-4I-SAE
SST25VF010A-33-4I-SAE-OZM
SST25VF010A-33-4I-SAE-OZM-T
SST25VF010A-33-4I-SAE-T
SST25VF020-20-4C-SAE
SST25VF020-20-4C-SAE-CC004
SST25VF020-20-4C-SAE-CC004-T
SST25VF020-20-4C-SAE-T
SST25VF020-20-4E-SAE
SST25VF020-20-4E-SAE-T
SST25VF020-20-4I-SAE
SST25VF020-20-4I-SAE-T
SST25VF020B-80-4C-SAE
SST25VF020B-80-4C-SAE-HCE
SST25VF020B-80-4C-SAE-HCE-T
SST25VF020B-80-4C-SAE-T
SST25VF020B-80-4C-SAE-TT078
SST25VF020B-80-4C-SAE-TT078-T
SST25VF020B-80-4I-SAE
SST25VF020B-80-4I-SAE-T
SST25VF020B-80-4I-SAE-TT078
SST25VF040B-40-4C-SAE-CT047
SST25VF040B-40-4C-SAE-CT047-T
SST25VF040B-40-4C-SAE-CT048
SST25VF040B-40-4C-SAE-CT048-T
SST25VF040B-40-4C-SAE-CT049
SST25VF040B-40-4C-SAE-CT049-T
SST25VF040B-40-4C-SAE-CT052
SST25VF040B-40-4C-SAE-CT052-T
SST25VF040B-40-4C-SAE-TT069
SST25VF040B-40-4C-SAE-TT069-T
SST25VF040B-40-4C-SAE-TT078
SST25VF040B-40-4C-SAE-TT078-T
SST25VF040B-40-4I-SAE-TT078
SST25VF040B-40-4I-SAE-TT078-T
SST25VF040B-50-4C-SAE-TT078
SST25VF040B-50-4C-SAE-TT078-T
SST25VF040B-80-4I-SAE

SST25VF040B-80-4I-SAE-100
SST25VF040B-80-4I-SAE-100-T
SST25VF040B-80-4I-SAE-T
SST25VF080B-80-4C-SAE
SST25VF080B-80-4C-SAE-T
SST25VF080B-80-4I-SAE
SST25VF080B-80-4I-SAE-T
SST25VF512-20-4C-SAE
SST25VF512-20-4C-SAE-CT027
SST25VF512-20-4C-SAE-CT027-T
SST25VF512-20-4C-SAE-T
SST25VF512A-33-4C-SAE
SST25VF512A-33-4C-SAE-T
SST25VF512A-33-4I-SAE
SST25VF512A-33-4I-SAE-T



QUALIFICATION REPORT

RELIABILITY LABORATORY

PCN #: CYER-19IFTH566

Date
July 17, 2012

Qualify 8L SOIC, package code SAE, with MSL level 1 at LPI assembly site.

Distribution

Somnuek T.
Wanphen L.
Wichai K.
Chalermpon P.

Rangsun K.
C.K. Barlingay
R. Sharma

Microchip Technology (Thailand) Co., Ltd.
14 Moo 1 T.Wangtakien A. Muangchacherngsao,
Chacherngsao, Thailand, 24000
Tel. (+66 38) 857119-45, 857311-19 ext. 1231
Fax (+66 38) 857149-50



MICROCHIP

PACKAGE QUALIFICATION REPORT

Purpose	Qualify 8L SOIC, package code SAE, with MSL level 1 at LPI assembly site.
CN	BC120613
QUAL ID	Q12037
MP CODE	X0005TC2XH80
Part No.	SST25VF080B-80-4I-SAE-T
Bonding No.	A-041549 Rev. A
CCB No.	1148.01
<u>Package</u>	
Type	8L SOIC
Package size	150 mils
Die thickness	19 mils
Die size	73.70 x 95.74 mils
<u>Lead Frame</u>	
Paddle size	95 x 130 mils
Material	C194
Surface	Ag plate
Process	Stamp
Lead Lock	No
Part Number	8LSOP-LINGSEN-9513S
<u>Die attach material</u>	
Epoxy	8340
Wire	Au wire
Mold Compound	G600
Plating Composition	Matte Tin



MICROCHIP PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Trace Code
LPI-130300004.000	M08A911276760.000	1216RH9
LPI-130300006.000	M08A911276760.000	1216RHB
LPI-130300007.000	M08A911276760.000	1216RHC

Result

☒ Pass ☐ Fail ☐ _____

8L SOIC assembled by LPI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

Prepared By: _____ Date: July 17, 2012 (Reliability Engineer)

(Mr.Udom Suksansakul)

Approved By: _____ Date: July 17, 2012 (Reliability Manager)

(Mr. Somnuek Thongprasert)

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
<u>MSL</u>								
MSL Level 1/260°C	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020D)	S12/14/16 (PDC)	135	05/24/12	05/31/12	0/135	Pass	

<u>Precondition</u>								
Electrical Test	Electrical Test +25°C and 95°C System: NEXTEST_PV2	S12/14/16 (PDC)	693(0)	05/17/12	05/21/12	693		Good Devices
Bake	Bake 150°C, 24 hrs System: CHINEE	PI-92014B		05/23/12	05/24/12	693		
Moisture Soak	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH	PI-91173B		05/24/12	05/31/12	693		
Convection-Reflow	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243	PI-91160B		05/31/12	05/31/12	693		
Electrical Test	Electrical Test :+25°C and 95°C System: NEXTEST_PV2	S12/14/16 (PDC)		06/01/12	06/01/12	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H Inspection: External crack inspection all units under 40X Optical magnification	PI-91020B		06/05/12	06/16/12	231		Parts had been pre-conditioned at 265°C
		QCI-33003	30(0)	06/16/12	06/16/12	0/30		
	Electrical Test: + 95°C System: NEXTEST_PV2	S12/14/16 (PDC)	231(0)	06/16/12	06/18/12	0/231	Pass	77 units / lot
UNBIASED-HAST	Bond Strength: Bond Shear (6.80 grams) Wire Pull (> 3 grams)	QCI-91022	15 (0)	06/18/12	06/18/12	0/15	Pass	
			15 (0)	06/18/12	06/18/12	0/15	Pass	
	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	PI-91261B		06/05/12	06/09/12	231		Parts had been pre-conditioned at 265°C
	Electrical Test: +25°C System: NEXTEST_PV2	S12/14/16 (PDC)	231(0)	06/09/12	06/11/12	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Microchip Spec	Qty. (Acc.)	Date in	Date Out	Def/SS.	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 3.6 Volts System: HAST 6000X	PI-92010B		06/05/12	06/09/12	231		Parts had been pre-conditioned at 265°C
	Electrical Test: +25°C and 95°C System: NEXTEST_PV2	S12/14/16 (PDC)	231(0)	06/09/12	06/11/12	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	PI-92014B S12/14/16		05/23/12	06/15/12	45		45 units
	Electrical Test: +25°C and 95°C System: NEXTEST_PV2	(PDC)	45(0)	06/15/12	06/17/12	0/45	Pass	
Bond Strength Data Assembly	Bond Shear (6.80 grams)	QCI-91022	30 (0) bonds	-	-	0/30	Pass	
	Wire Pull (> 3 grams)		30 (0) wires	-	-	0/30	Pass	